

METHOD AND PROCESSING SYSTEM FOR PLASMA-ENHANCED  
CLEANING OF SYSTEM COMPONENTS

ABSTRACT OF THE DISCLOSURE

A method for plasma-enhanced cleaning of a system component in a batch-type processing system and a method for monitoring and controlling the cleaning. The cleaning is performed by introducing a cleaning gas in a process chamber of the batch-type processing system, forming a plasma by applying power to a system component within the process chamber, exposing a material deposit in the process chamber to the plasma to form a volatile reaction product, and exhausting the reaction product from the processing system. Monitoring of the processing system can be carried out to determine cleaning status of the processing system, and based upon the status from the monitoring, the processing system is controlled for either continuing the exposing and monitoring or stopping the cleaning process. A batch-type processing system is provided that allows plasma-enhanced cleaning of system components, and a system is provided with monitoring and controlling capability.